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substrate surface, and reducing the power of the laser for the activation of the substrate surface.

6. (Amended) A method according to claim 1, comprising depositing further metal on the electrolessly plated region of the substrate.

9. (Amended) A method according to claim 1, comprising ablating the substrate material underlying the ablated area of the strippable coating to form a recess in the substrate material before activating the polymer surface.

11. (Amended) A method according to claim 1, comprising using the laser to ablate the strippable coating, selectively activate the substrate surface and drill a landless via in the substrate material in the same step.

14. (Amended) A method according to claim 1, comprising selectively plating non-planar features on the substrate surface.

15. (Amended) A method according to claim 1, comprising forming an integrated resistor by selectively activating and plating a region between two circuit interconnects on the substrate surface.

17. (Amended) A method according to claim 1 used to re-map a wafer.